

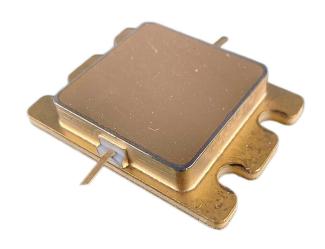
MCNI8596-P52

X-Band Internally Matched GaN Device

Key Features

■ Operating Frequency: 8.50-9.60 GHz
 ■ Saturated Output Power (Psat): ≥ 52 dBm

Power Gain(Gp): ≥8dB
Work Efficiency (η): ≥ 36%
Port Matching: Zin/Zout = 50 Ω



Product Description

The MCNI8596-P52 is an internal matching GaN device, which adopts advanced co-planar internal matching MCM and thin film circuit technology. The typical working frequency range is 8.50-9.60GHz.

This device can be used in different RF/Microwave system and subsystem. The high output power level, high efficiency and wide operating temperature range can make application very flexible.

Absolute Maximum Ratings (Tc=25°C)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_Ds	40	V
Gate-Source Voltage	V _{GS}	-5	V
Storage Temperature	Tstg	-65 to +150	°C
Channel Temperature	Tch	150	°C

^{*}Not recommended to work under these conditions.

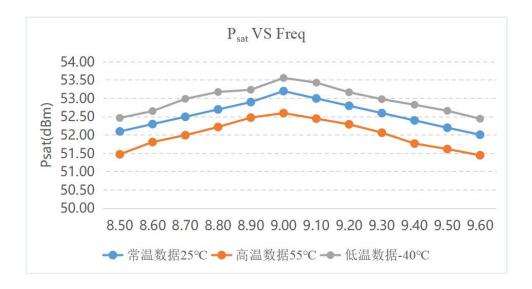
Microwave Electrical Characteristics

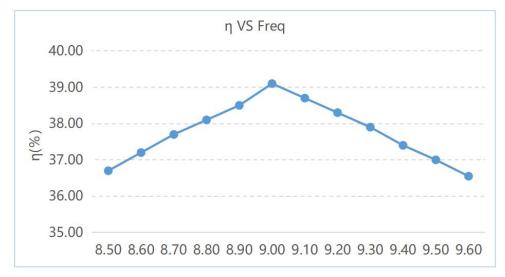
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Drain Current	dsr	VDS:28V Pulse Operation T=1ms,Duty=10% Pin: 44dBm Freq: 8.5~9.6GHZ	-	15.7	-	Α
Saturated Output Power	P _{sat}		52	-	-	dBm
Power Gain	Gp		8	-	-	dB
Work Efficiency	η		36	-	-	%
Gain Flatness	ΔG		-0.8	-	0.8	dB

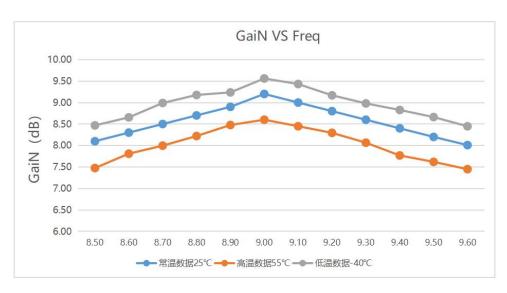


X-Band Internally Matched GaN Device

Typical Curves







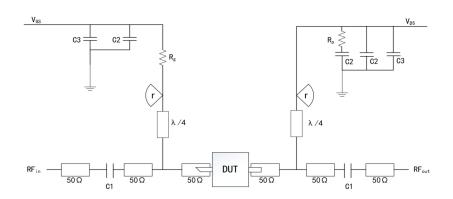
2





X-Band Internally Matched GaN Device

Recommended Application Circuit



DUT: Device Under Test

C1:1pF Rp:51 Ω C2:1000pF Rg:15 Ω

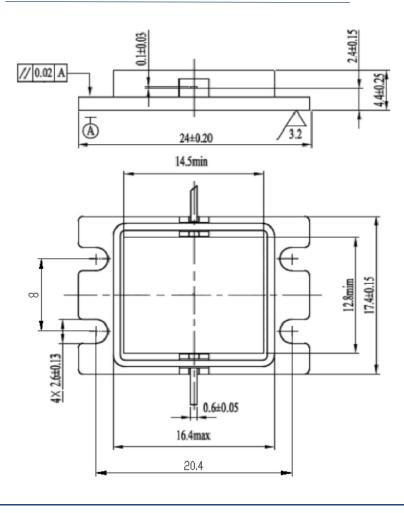
C3:100uF

Radius ≈ 3.5mm (Rogers 5880, 20 mil)

ESD Level

ESD	Class III	2000V

Overall Dimensions



Using Notes:

- During transportation and storage, ensure proper drying.
- During the use and assembly of the chip, take precautions against static electricity. Wear a grounded anti-static wristband.
- When powering on, apply gate voltage first, then apply leakage voltage.